

MA2J1140G

Silicon epitaxial planar type

For small power rectification

■ Features

- S-mini type package, allowing high-density mounting
- High reverse voltage V_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	150	V
Maximum peak reverse voltage	V_{RM}	150	V
Output current	I_O	200	mA
Repetitive peak forward current	I_{FRM}	600	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $t = 1\text{ s}$

■ Package

- Code
SMini2-F3
- Pin Name
1: Anode
2: Cathode

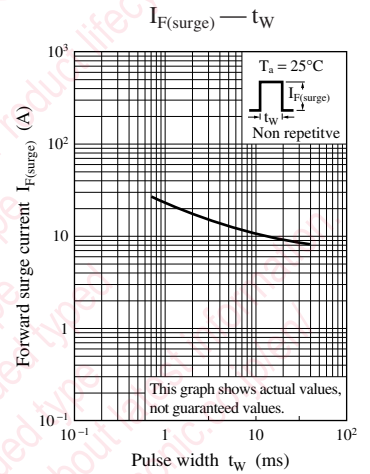
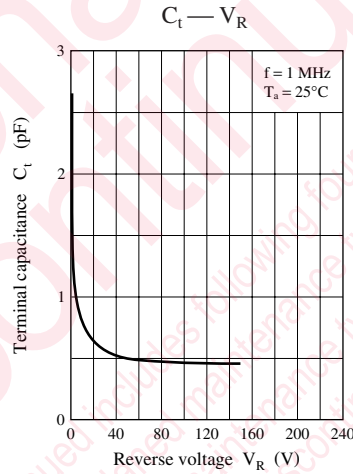
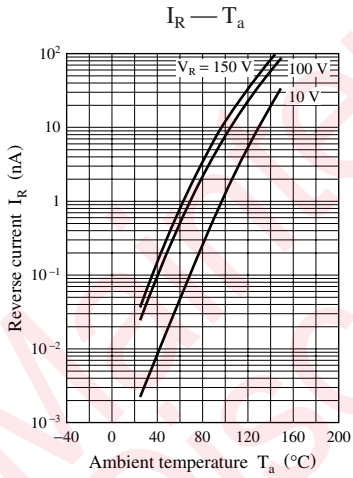
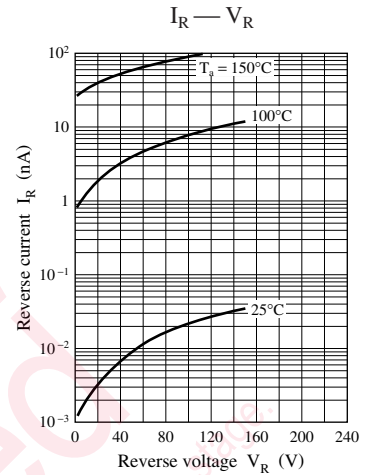
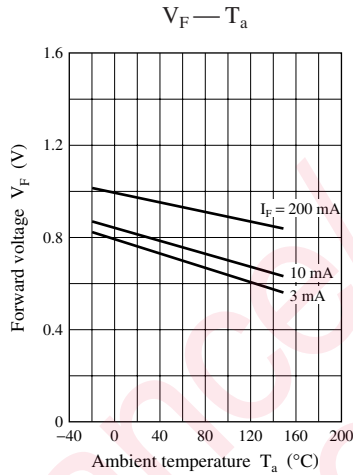
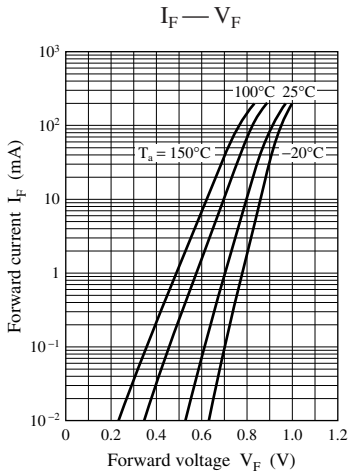
■ Marking Symbol: 1E

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200\text{ mA}$			1.2	V
Reverse current	I_R	$V_R = 150\text{ V}$			200	nA
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		4.5		pF

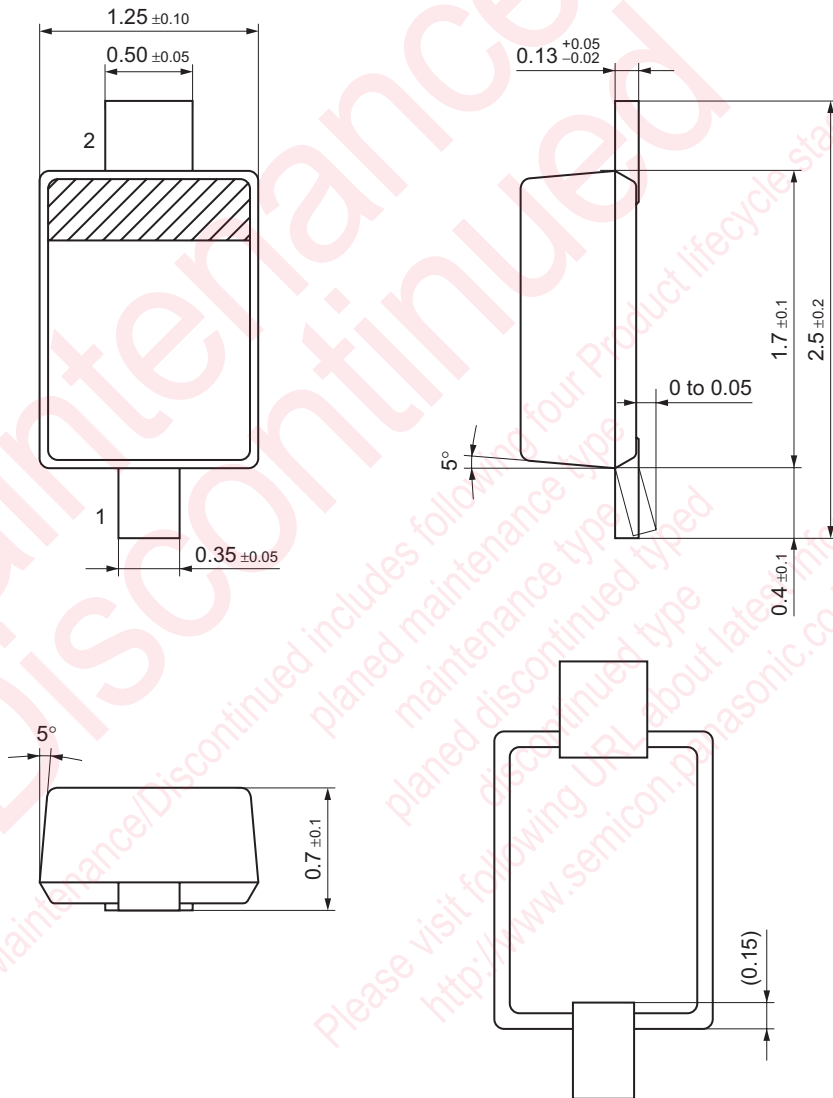
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 3 MHz.



SMini2-F3

Unit: mm



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